

Title (en)  
SANDWICH-STRUCTURED INTELLIGENT POWER MODULE

Title (de)  
INTELLIGENTES LEISTUNGSMODUL IN SANDWICH-BAUWEISE

Title (fr)  
MODULE DE PUISSANCE INTELLIGENT DE STRUCTURE SANDWICH

Publication  
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Application  
**EP 00938710 A 20000530**

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Abstract (en)  
[origin: WO0074445A1] According to the invention, the power substrate is used as a base plate in a housing (1) which, together, form a standardized power part from whose top surface (11) connection pins (5) project. Said projection pins are soldered inside interfacial connection via holes of the control printed circuit board (4). The printed circuit board (4) comprises contact pads (7) which are located in an open strip area (6) and which serve as control terminals and power terminals by means of which the module can be soldered directly into the slotted opening of a system printed circuit board (8).

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IPC 8 full level  
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